

AMENDMENT TO THE CLAIMS:

This listing of claims will replace all prior versions of claims in the application:

LISTING OF CLAIMS:

1. (CANCEL)
2. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the substrate is flexible.
3. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the substrate is substantially resilient.
4. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the at least one diode includes crossed diodes.
5. (ORIGINAL) A device as recited in claim 4, wherein the crossed diodes include multiple diodes aligned in series in each direction.
6. (CURRENTLY AMENDED) A device as recited in claim [[5]] 9, wherein a number of diodes in one bias direction is different than a number of diodes in another bias direction.
7. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the at least one diode has a response time of less than about 20 nanoseconds.
8. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the at least one diode is contained in a chip, wherein the chip is coupled to the substrate.

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9. (CURRENTLY AMENDED) A reusable device as recited in claim 1, for protecting an electronic component from electrostatic discharge (ESD), comprising:
a substrate having a coupling region being adapted for detachable coupling to at least one of a cable and another device;
at least one diode coupled to the substrate; and
contact leads coupled to the coupling region of the substrate, the contact leads being in electrical communication with the at least one diode,
wherein a compression fitting is used to couple the coupling region of the substrate to the cable or the other device.
10. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the device is used during testing of tape heads.
11. (CURRENTLY AMENDED) A device as recited in claim [[1]] 9, wherein the device is used during testing of disk heads.
12. (CANCEL)
13. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein the substrate is flexible.
14. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein the substrate is substantially resilient.
15. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein each pair of crossed diodes include multiple diodes aligned in series in each direction.

16. (CURRENTLY AMENDED) A device as recited in claim [[15]] 17, wherein a number of diodes in one bias direction is different than a number of diodes in another bias direction.
17. (CURRENTLY AMENDED) A device as recited in claim 12, for protecting an electronic component from electrostatic discharge (ESD), comprising:
a substrate having at least one coupling region being adapted for coupling to at least one of a cable and another device;
at least one pair of crossed diodes coupled to the substrate; and
contact leads coupled to the coupling region of the substrate, the contact leads
being in electrical communication with the at least one diode,
wherein the diodes have a response time of less than about 20 nanoseconds.
18. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein the diodes are contained in a chip, wherein the chip is coupled to the substrate.
19. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein a compression fitting is used to couple the coupling region of the substrate to the cable or the other device.
20. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein the device is used during testing of tape heads.
21. (CURRENTLY AMENDED) A device as recited in claim [[12]] 17, wherein the device is used during testing of disk heads.
22. (ORIGINAL) A reusable device for protecting a magnetic head from electrostatic discharge (ESD) during testing of the magnetic head, comprising:
a substrate having first and second coupling regions, the first coupling region
being adapted for coupling to a cable, the second coupling region being

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adapted for detachable coupling to at least one of a second cable and another device;

crossed diodes coupled to the substrate, a pair of the crossed diodes being present for each element of the magnetic head being tested, each pair of crossed diodes including multiple diodes aligned in series in each direction, wherein the diodes have a response time of less than about 20 nanoseconds; and

contact leads coupled to the coupling region of the substrate, the contact leads being in electrical communication with the crossed diodes.